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Radiation Induced Defects in 8T-CMOS Global Shutter Image Sensor for Space Application

<u>A. Le Roch</u>, V. Goiffon, C. Durnez, P. Magnan Université de Toulouse, ISAE SUPAERO, 31055 Toulouse, France.

C. Virmontois, L. Pistre, J-M. Belloir Centre National d'Etudes Spatiales (CNES), 31400 Toulouse, France.





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- Particles from space and nuclear radiation environments are likely to generate Displacement Damage Dose (DDD).
- Displaced Si atoms create stable defects. Such defects act as generation centers and lead to a dark current increase.
- Defects creation mechanisms and annealing behaviors are needed for a better understanding of radiation induced dark current increase
- The main goal is to find a mitigation technique.





 DCS is used to charaterize radiation induced defects throughout the dark current distribution of all the pixels of the matrix.



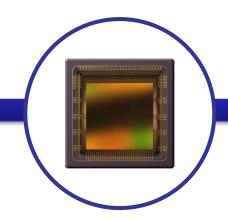


- DCS is used to charaterize radiation induced defects throughout the dark current distribution of all the pixels of the matrix.
- The per pixel dark current relies on silicon sampled by the PPD depleted volume.





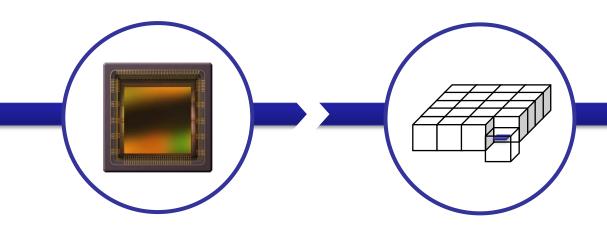
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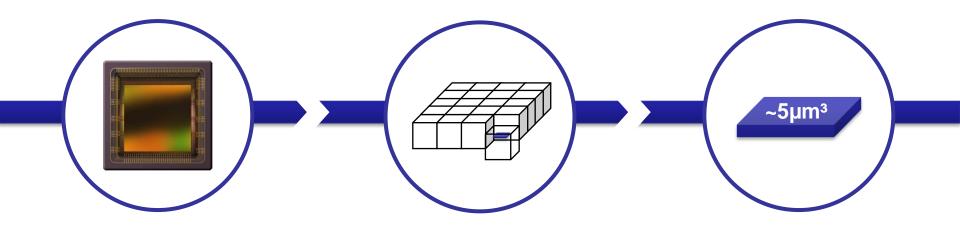
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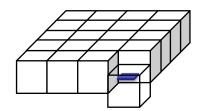
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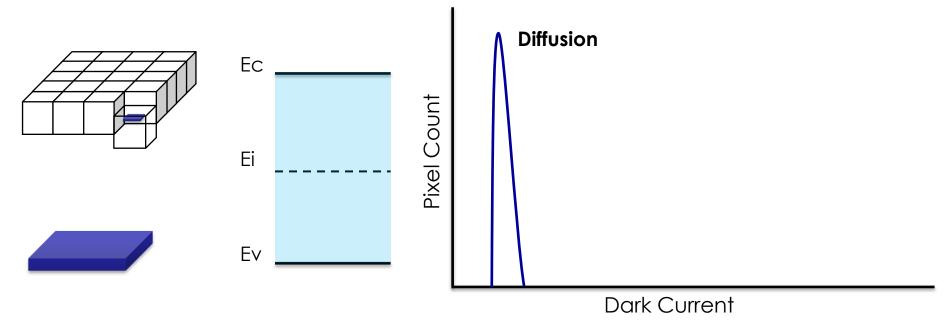








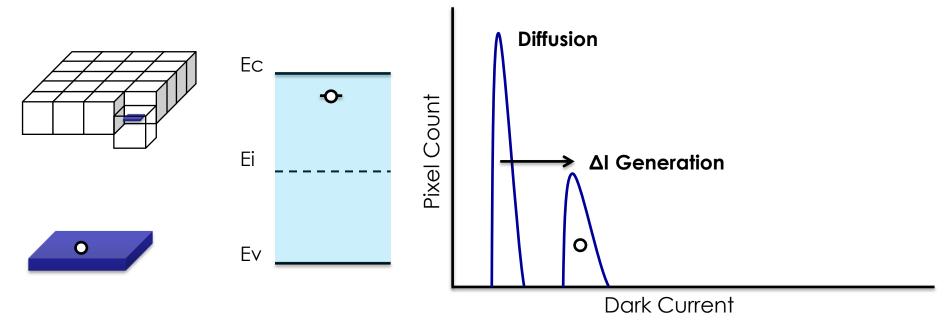
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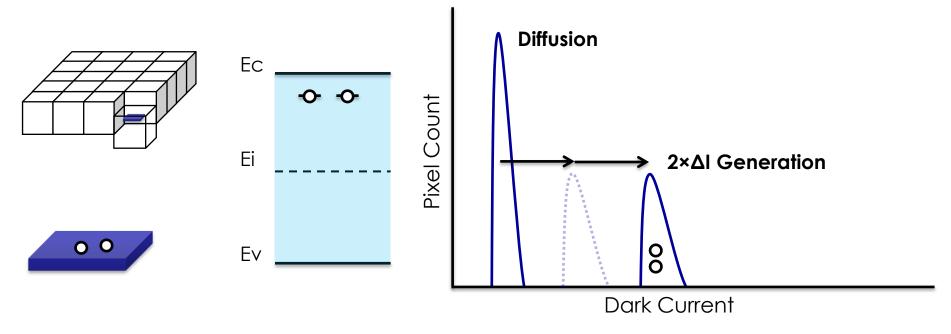
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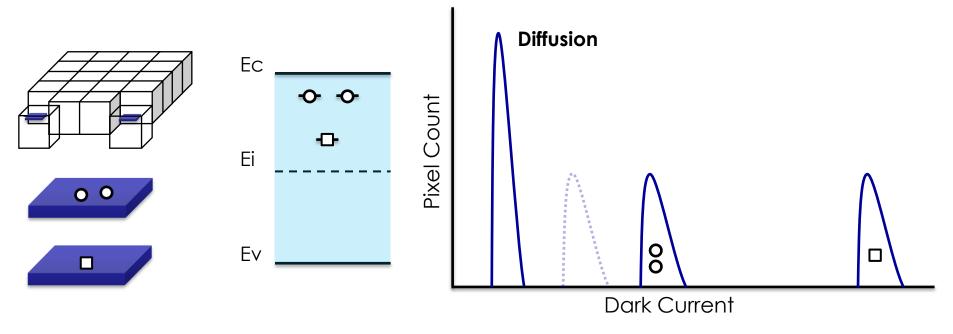
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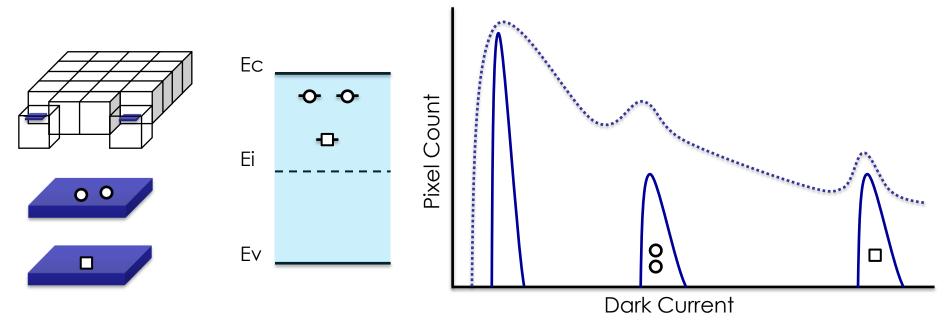
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The generation dark current expression of a stable defect with energy level E_t is given by:

$$I_{dc} \approx A \cdot \exp(-\frac{\frac{E_g}{2} - |\mathbf{E_t} - E_i|}{k_B \cdot T})$$

 E_g Silicon band GAP

 E_t Defect energy level

 E_i Silicon mid-GAP

 k_B Boltzmann Constant

T Temperature

o The dark current temperature evolution leads to defect activation energy estimation labeled E_a with the Arrhenius law.

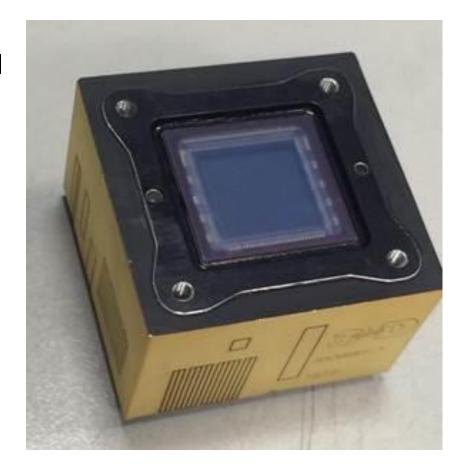
$$I_{dc} \approx A \cdot e^{\frac{-E_a}{k_B \cdot T}}$$
 $E_a \approx \frac{E_g}{2} - |E_t - E_i|$



COTS Imager



- The CIS under test is a (Commercial Off-The-Shelf) COTS imager
 - 2048×2048 pixels
 - 0.18µm technology
 - 8T-PPD
 - Global shutter
 - 5.5 µm pitch pixels
 - PPD depleted volume of 5µm³
- This CIS is integrated in a microcamera for CNES space missions.



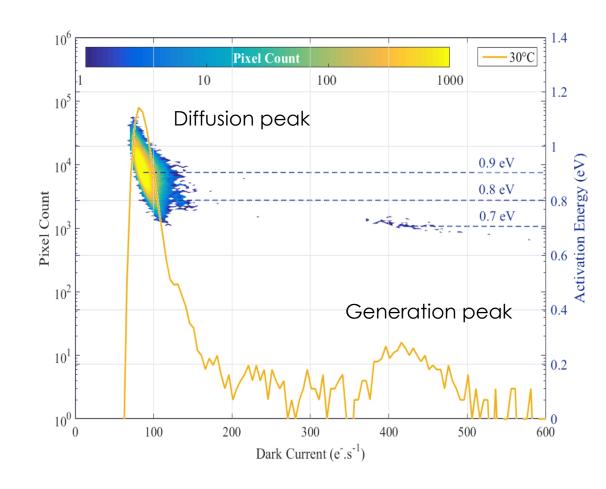


Dark Current distribution Before Irradiation



Dark current and activation energy distribution plotted at 20°C

 Diffusion peak containing pixels without defect in the microvolume.



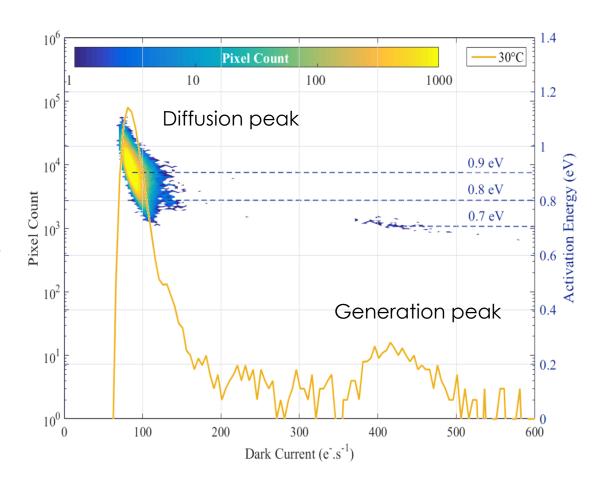


Dark Current distribution Before Irradiation



Dark current and activation energy distribution plotted at 20°C

- Diffusion peak containing pixels without defect in the microvolume.
- Generation peak due to CMOS foundry process.

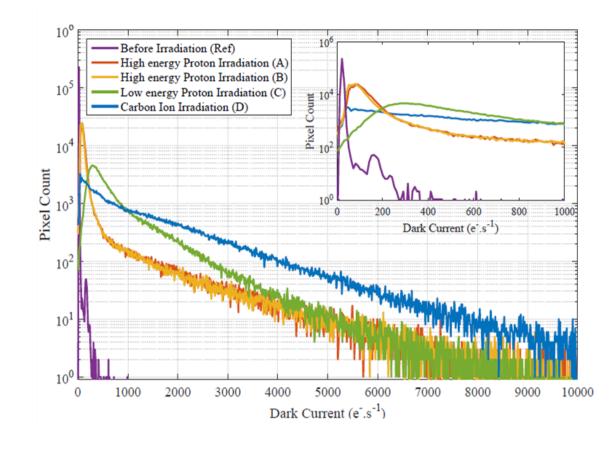




Irradiations Parameters



- High energy proton (A-50MeV B-150 MeV)
 - Nuclear chocs
 - Cascade of defects

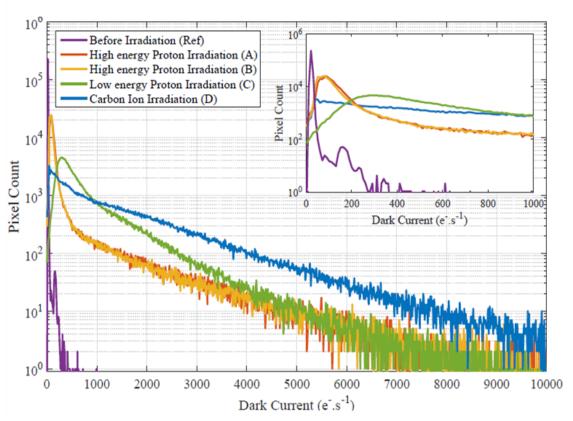




Irradiations Parameters



- High energy proton (A-50MeV B-150 MeV)
 - Nuclear chocs
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- Carbon ion (D-10 MeV)
 - Nuclear chocs and Coulombic interaction
 - Cascade of defects and Point defects



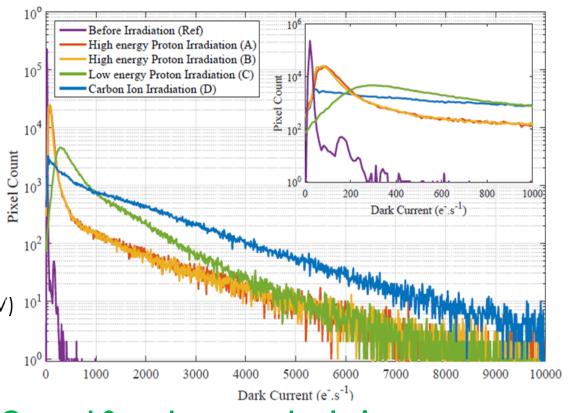


Irradiations Parameters



- High energy proton (A-50MeV B-150 MeV)
 - Nuclear chocs
 - Cascade of defects
- Carbon ion (D-10 MeV)
 - Nuclear chocs and Coulombic interaction
 - Cascade of defects and Point defects
- Low energy proton (C-1 MeV)
 - Coulombic interaction
 - Point defects

Best case for the Dark Current Spectroscopy technique



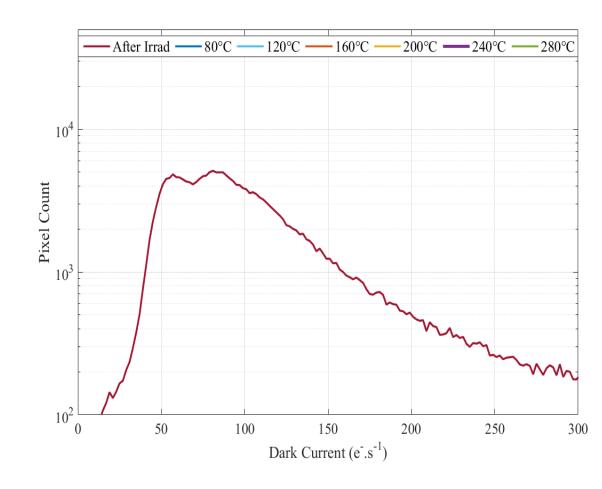




Highenergy proton







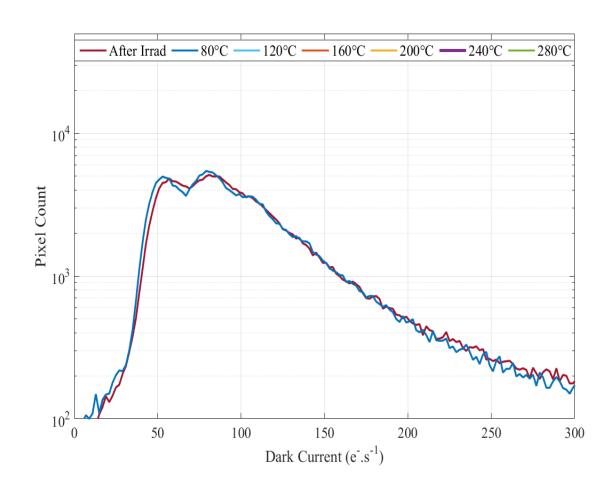




Highenergy proton







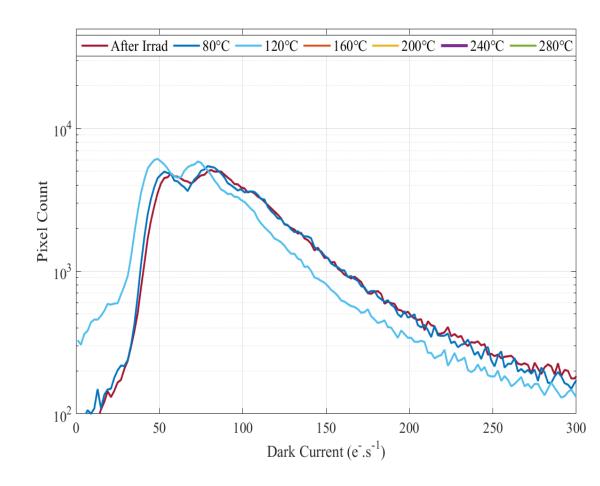




Highenergy proton







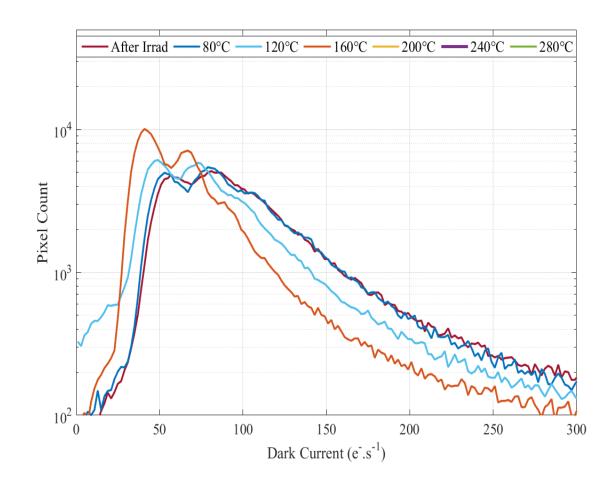




Highenergy proton







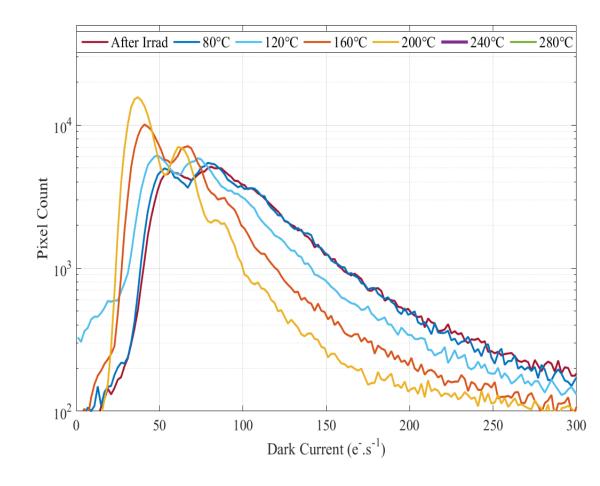




Highenergy proton







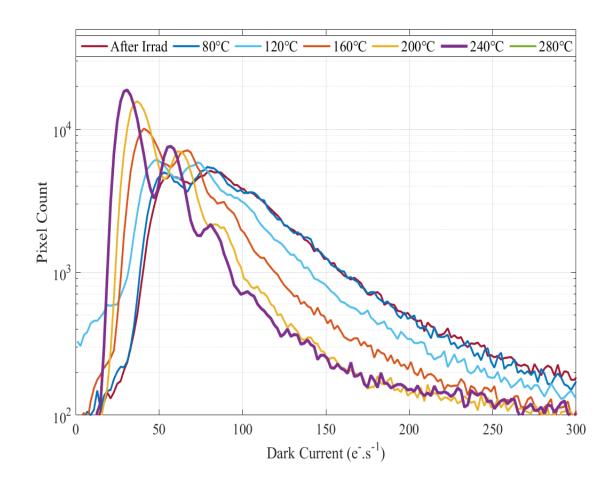




Highenergy proton







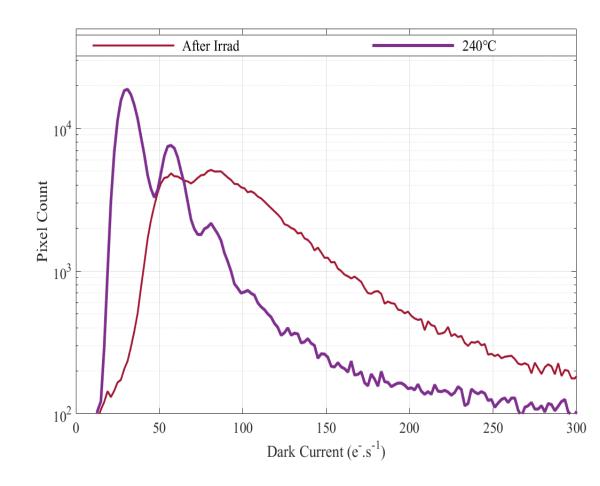




Highenergy proton







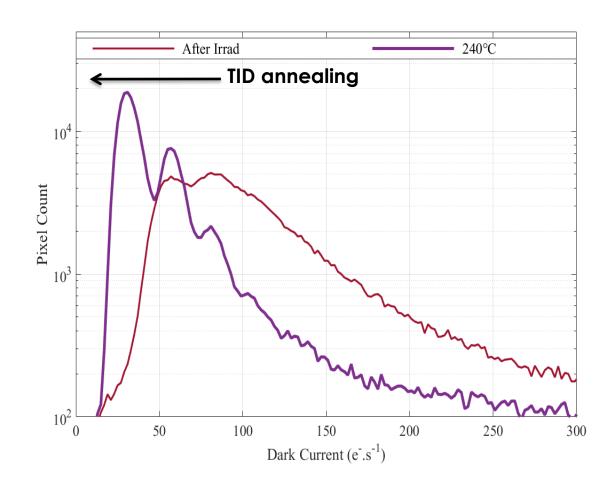




- Highenergy proton
- Dark current distribution evolution with annealings plotted at 20°C
 - TID annealing



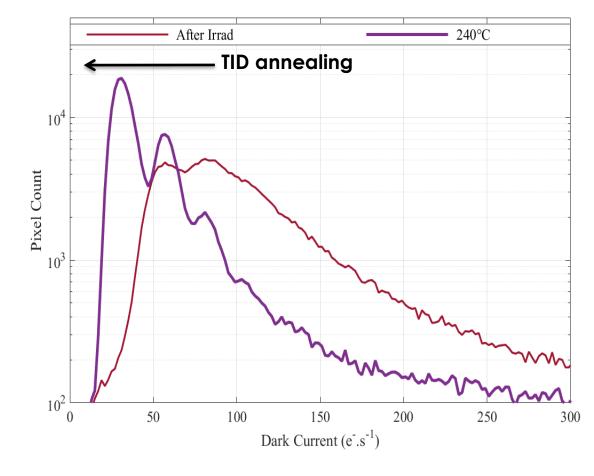








- Highenergy proton
- Dark current distribution evolution with annealings plotted at 20°C
 - TID annealing
 - Increase of the diffusion peak.



2 Carborion

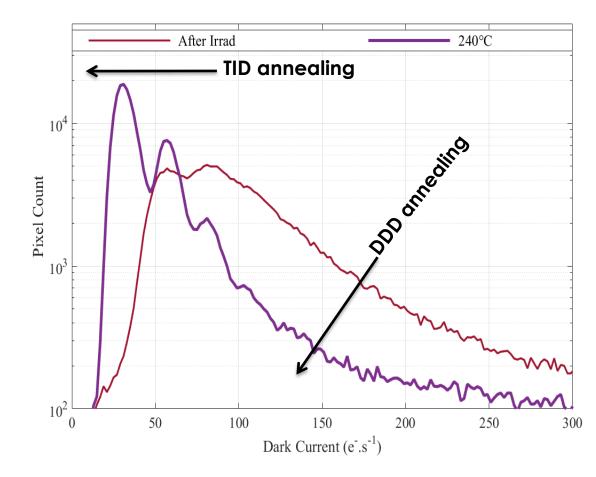
3 Low energy proton





Highenergy proton

- Dark current distribution evolution with annealings plotted at 20°C
 - TID annealing
 - Increase of the diffusion peak.
 - Decrease of the dark current tail.



3 Low energy proton

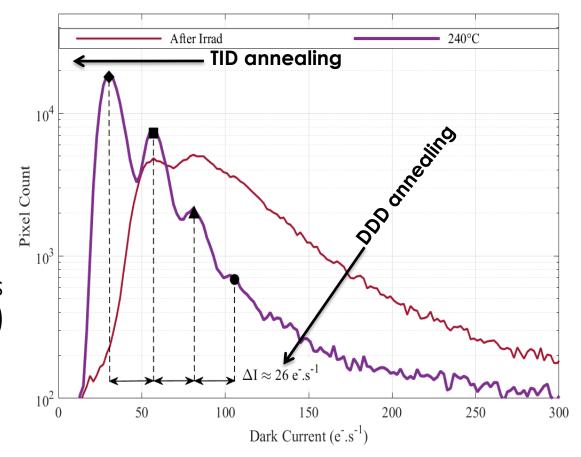
ion





Highenergy proton Dark current distribution evolution with annealings plotted at 20°C

- TID annealing
- Increase of the diffusion peak.
- Decrease of the dark current tail.
- Multiple generation peaks
 ΔI = 26 e-/s (20°C)



3 Low energy proton

ion

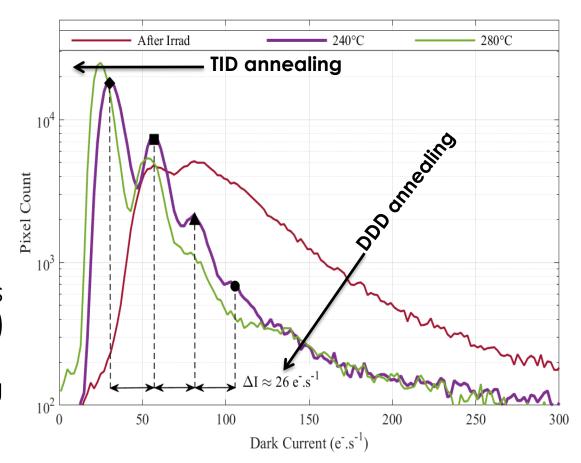


High Energy Proton



Highenergy proton Dark current distribution evolution with annealings plotted at 20°C

- TID annealing
- Increase of the diffusion peak.
- Decrease of the dark current tail.
- Multiple generation peaks
 ΔI = 26 e-/s (20°C)
- Defect annealing between 240°C and 280°C.



3 Low energy proton

ion



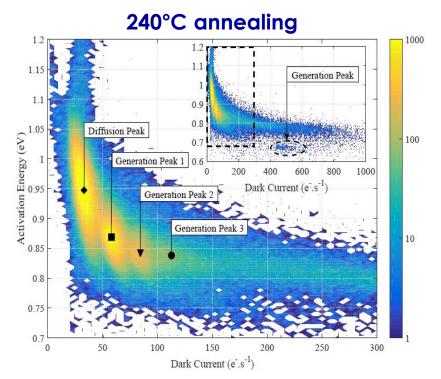
High Energy Proton

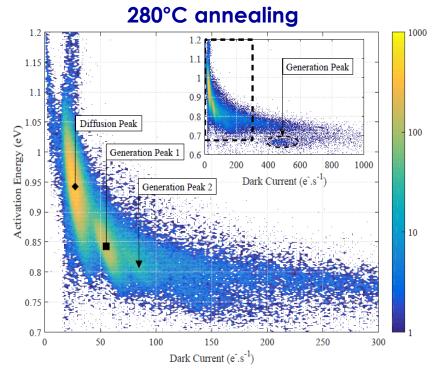


- Highenergy proton
- Activation energy evolution with annealings (240°C and 280°C)
 - Dark current △I = 26 e-/s (20°C)
 - Activation energy Ea = 0,83eV
 - Annealing temperature [240°C 280°C]



Low energy proton







Carbon Ion



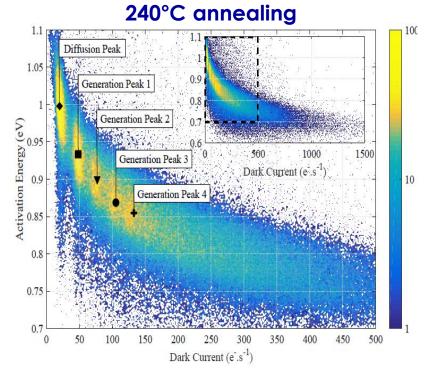
Highenergy proton

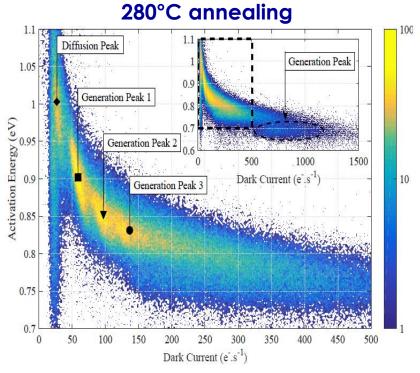
- Activation energy evolution with annealings (240°C and 280°C)
 - Dark current △I = 30 e-/s (20°C)
 - Activation energy Ea = 0,83eV
 - Annealing temperature [240°C 280°C]



3 Low energy proton

Alexandre Le Roch







Carbon Ion



Highenergy proton

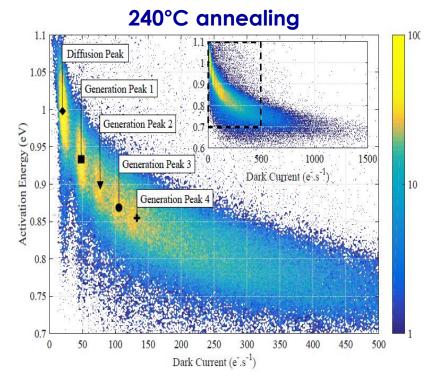
Activation energy evolution with annealings (240°C and 280°C)

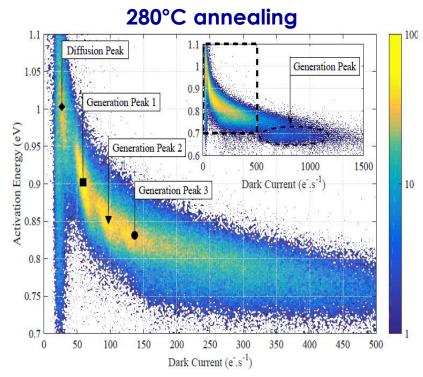
- Dark current ΔI = 30 e-/s (20°C)
- Activation energy Ea = 0,83eV
- Annealing temperature [240°C 280°C]

Same defects identification after high energy proton

2 Carbon ion

3 Low energy proton





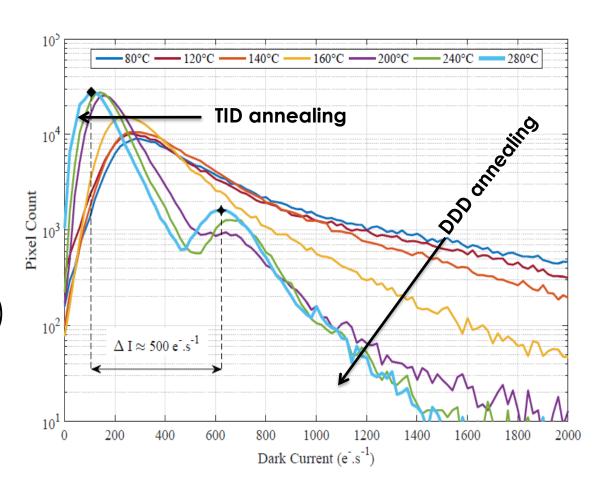


Low Energy Proton



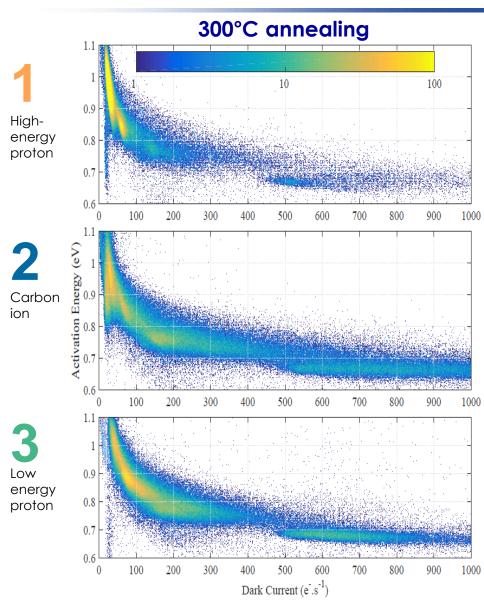
Highenergy proton

- Dark current distribution evolution with annealings plotted at 20°C
- TID annealing
- Increase of the diffusion peak.
- 2 Carbon
- Decrease of The dark current tail.
- Generation peaks $\Delta I = 500 \text{ e-/s} (20^{\circ}\text{C})$
- No annealing between 240°C and 280°C.





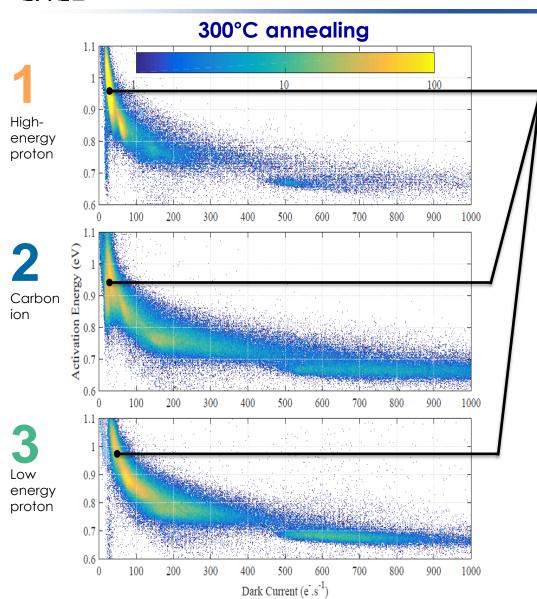




Last annealing at 300°C







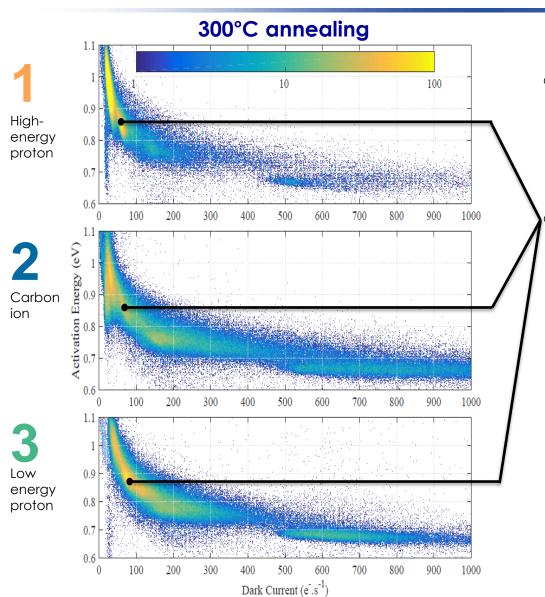
Last annealing at 300°C

Diffusion peak

- Idc ~ 30e-/s (20°C)
- Ea ~ 0,95eV







Last annealing at 300°C

Diffusion peak

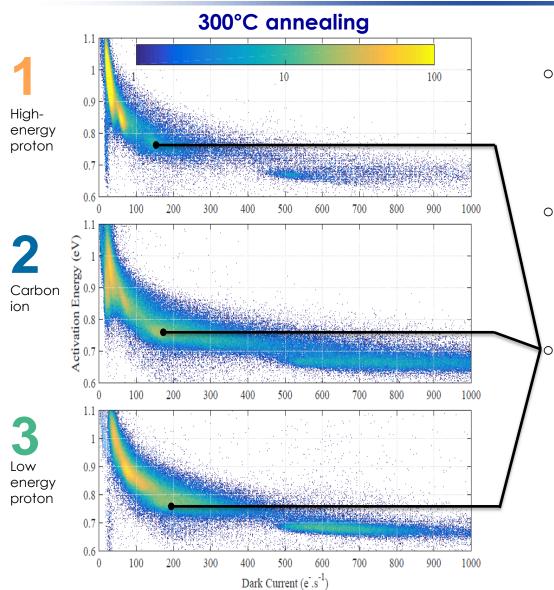
- Idc ~ 30e-/s (20°C)
- Ea ~ 0,95eV

First generation peak (remaining)

- ΔIdc ~ 30e-/s (20°C)
- Ea ~ 0,83eV







Last annealing at 300°C

- Diffusion peak
 - Idc ~ 30e-/s (20°C)
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First generation peak (remaining)

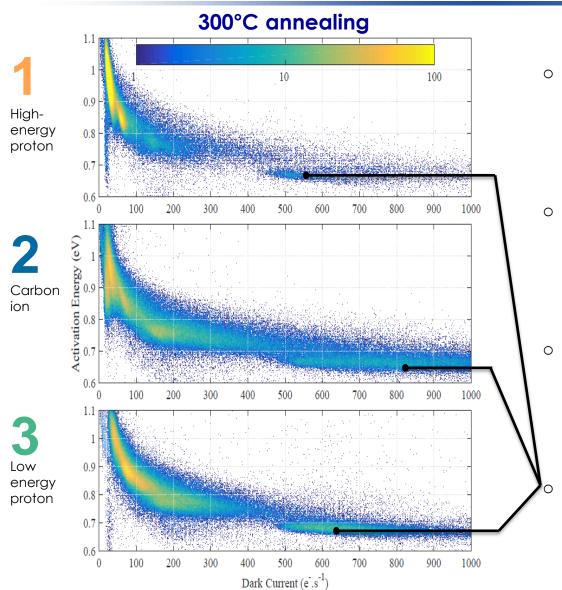
- ΔIdc ~ 30e-/s (20°C)
- Ea ~ 0,83eV

Second generation peak?

- Δ Idc ~ 150e-/s (20°C)
- Ea ~ 0,75eV







Last annealing at 300°C

- Diffusion peak
 - Idc ~ 30e-/s (20°C)
 - Ea ~ 0,95eV
- First generation peak (remaining)
 - ΔIdc ~ 30e-/s (20°C)
 - Ea ~ 0,83eV
 - Second generation peak?
 - Aldc ~ 150e-/s (20°C)
 - Ea ~ 0,75eV

Third generation peak

- Δ Idc ~ 600e-/s (20°C)
- Ea ~ 0,67eV

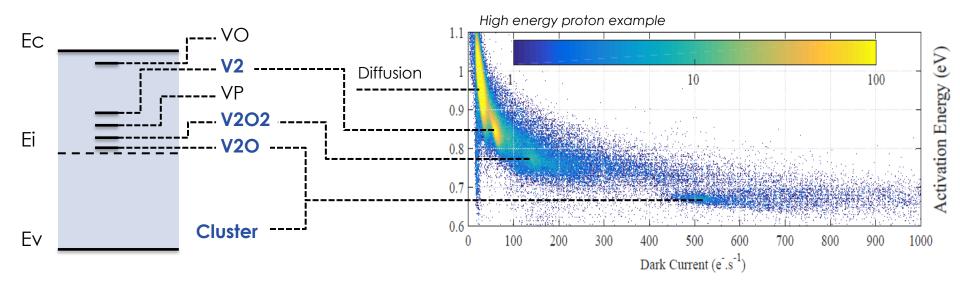


Defects Identification and Discussion



Defect	20°C Dark Current (e-/s)		Et-Ei (eV)		Annealing Temperature	
Vacancy-Oxygen VO		-		~0,39		> 300°C
Divacancy V2	~[26–30]	~30	~0,18	~0,17	[240°C-280°C]	260°C
Divacancy-Dioxygen V2O2	150	-	~0,11	~0,16	> 300°C	> 300°C
Vacancy-Phosphorus VP		~35		~0,13		150°C
Divacancy-Oxygen V2O	~[500–600]	-	~0,01	~0,06	> 300°C	> 330°C

Experimental Datas







- 4 COTS imagers have been irradiated with:
 - High energy proton / Carbon ion / Low energy proton





- 4 COTS imagers have been irradiated with:
 - High energy proton / Carbon ion / Low energy proton
- The hypothetical existence of oxygen based defects such as V2O and V2O2 have been pointed out.
 - The role of oxygen impurities in the dark current rise after irradiation.





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Oxygen concentration



Minimum impurity concentration in pure Si





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 - The role of oxygen impurities in the dark current rise after irradiation.



Oxygen concentration



Minimum impurity concentration in pure Si

The DCS measurements suggest that similar divancancy based defects are involved in all the irradiations.







Thanks for your attention

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Irradiations Parameters



IRRADIATION PARAMETERS

Sensor Ref	А	В	# (for UDF)	С	D
Particles	Proton	Proton	Proton	Proton	Carbon
Energy (Mev)	50	150	50	1	10
Fluence (cm-2)	1,30 E+11	3,00 E+11	2,00 E+11	3.00 E+8	1.00 E+10
DDD (Tev.g-1)	504,4	645	776	+	++
TID (KradSi)	20,49	21,02	315,2	-	-

High energy proton

- Good NIEL estimation
- DDD Nuclear chocs
- Cluster of defects

Low energy proton

- Huge NIEL at End Of Range (EOR)
- Huge DDD
- Coulombic interactions
- Point defects

Carbon ion

- Huge cross section and mass
- DDD Nuclear chocs
- Cluster of defects

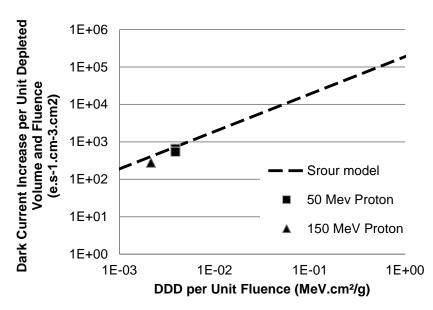


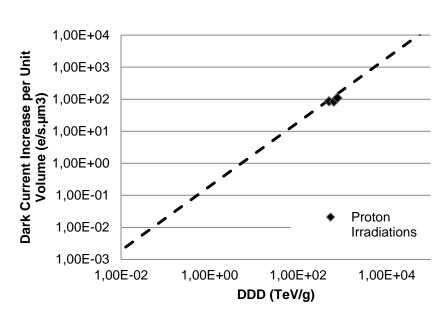
Universal Damage Factor (UDF)



Sensor Ref	Α	В	С
Particles	Proton	Proton	Proton
Energy (Mev)	50	150	50
Fluence (cm-2)	1,30 E+11	3,00 E+11	2,00 E+11
DDD (Tev.g-1)	504,4	645	776
TID (KradSi)	20,49	21,02	315,2
ΔI (e-/s)	415	424	542

$$V_{dep} = 5\mu m^3$$
 $K_{dark} = 1.9 \times 10^5 (e/\text{cm}^3.\text{s})/(\text{MeV/g})$



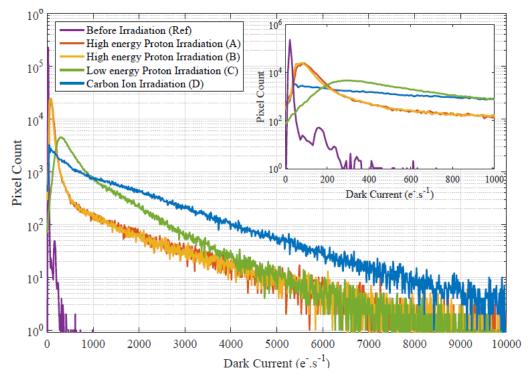


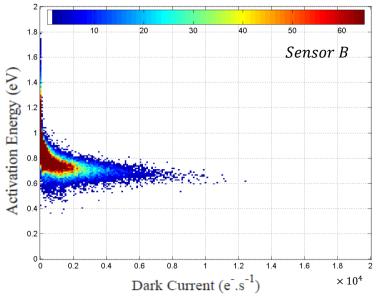


Dark Current Distribution



IRRADIATION PARAMETERS						
Sensor Ref	A	В	С	D		
Particles	Proton	Proton	Proton	Carbon		
Energy (Mev)	50	150	1	10		
Fluence (cm-2)	1,30 E+11	3,00 E+11	3.00 E+8	1.00 E+10		
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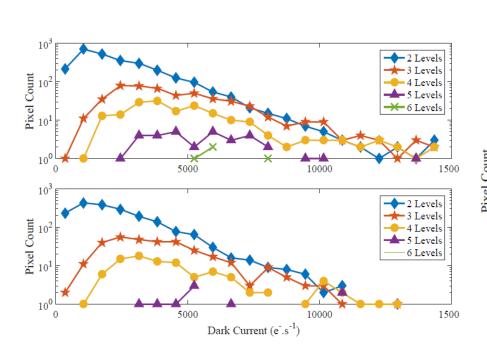


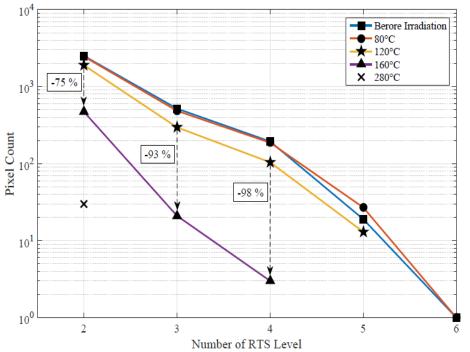




RTS Analysis 1









RTS Analysis 2



